

**METHOD OF MANUFACTURING AN IC PACKAGE**

**5    Abstract**

The invention provides a method for processing leadframe items to form IC packages, each of the leadframe items comprising an IC carried by a suitable leadframe, the leadframe items being of two or more types. The method  
10 includes receiving the two or more types of leadframe items along respective input paths, moving at least two holders alternately between a processing region and a respective leadframe item reception position, each of the holders moving to the processing region and at a time when the other of the holders moves to its respective reception position, the reception positions being on  
15 respective ones of the input paths, each of the holders receiving leadframe items of the respective type at the respective reception position and delivering them to the processing region and encapsulating the ICs at the processing position.

20    (FIG. 3)